Silicone-Free Thermal Interface Material Serves as a Gap Pad

W. L. Gore & Associates (Gore) has introduced its POLARCHIP SF3000 Silicone-Free Thermal Interface Material, a soft silicone-free thermal gap pad for silicone sensitive applications. This highly compressible, thermally conductive material is suited for filling the undesirable air gaps between heat generating devices on printed circuit boards and the heat sinks, heat spreaders and metal chassis that are used to dissipate the heat. The material is a fluoropolymer composite that consists of an expanded polytetrafluoroethylene (ePTFE) matrix filled with boron nitride (BN) particles. The low elastic modulus of the ePTFE matrix imparts softness, conformability and compressibility to the composite, while the high thermal conductivity of the BN particles gives the composite its thermal transport characteristics. The reinforcing nature of the ePTFE matrix results in a composite that is physically robust, easy to handle and does not require additional reinforcement. It is produced in continuous rolls with a pressure sensitive adhesive on one side.
W.L. Gore & Associates, Inc.
800-445-4673, www.gore.com [1]

Links:
[1] http://www.gore.com/